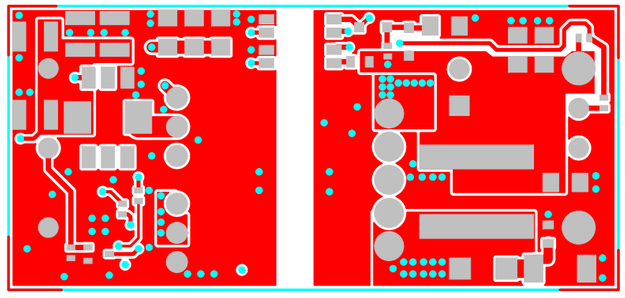
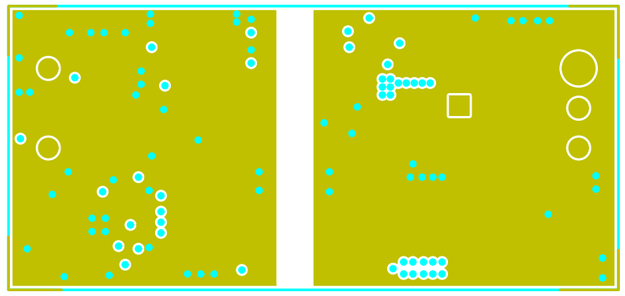
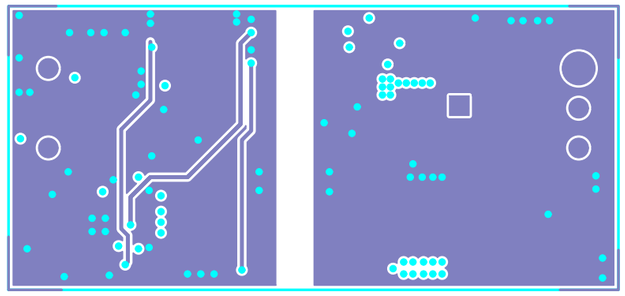


TEXAS INSTRUMENTS	Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
	Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP7451 / Rev. A	L1											

Date:	Filename:	Engineer:	PCB Dsgnr:	Modified Date:	Software
{Start Date}	PMP7451.PCB	B.KING	R.SMITH	{Modification Date}	PADs

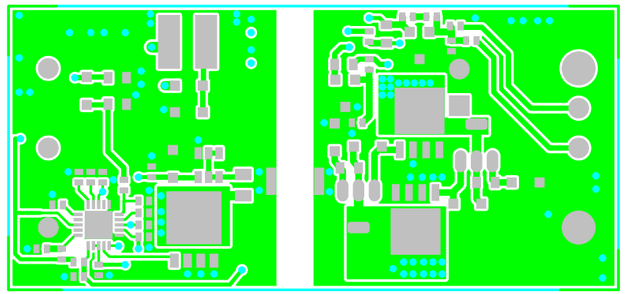


TEXAS INSTRUMENTS															Drill Drawing
		Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly			
		Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot		
Board No. PMP7451	Rev. A		L2												
Date: {Start Date}	Filename: PMP7451.PCB	Engineer: B.KING	PCB Dsgnr: R.SMITH	Modified Date: {Modification Date}									Software PADs		



TEXAS INSTRUMENTS	Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
	Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP7451 / Rev. A			L3										

Date:	Filename:	Engineer:	PCB Dsgnr:	Modified Date:	Software
{Start Date}	PMP7451.PCB	B.KING	R.SMITH	{Modification Date}	PADs



TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
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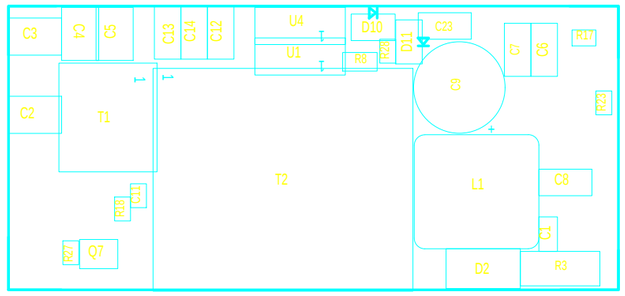
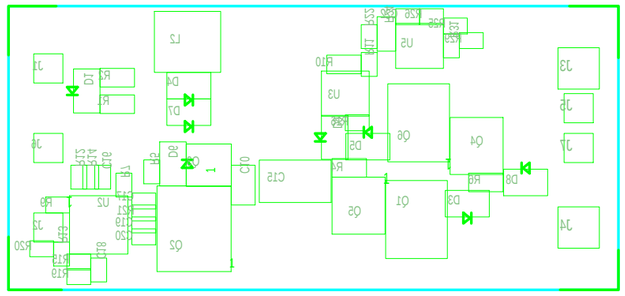
Board No. PMP7451	Rev. A				L4									

Date: {Start Date}	Filename: PMP7451.PCB	Engineer: B.KING	PCB Dsgnr: R.SMITH	Modified Date: {Modification Date}	Software PADs



TEXAS INSTRUMENTS			Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
			Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP7451	Rev. A		L1									TA		
Date: {Start Date}	Filename: PMP7451.PCB	Engineer: B.KING	PCB Dsgnr: R.SMITH	Modified Date: {Modification Date}								Software PADs		



TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
		Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP7451	Rev. A				L4								BA	
Date: {Start Date}	Filename: PMP7451.PCB	Engineer: B.KING	PCB Dsgnr: R.SMiTH	Modified Date: {Modification Date}								Software PADs		

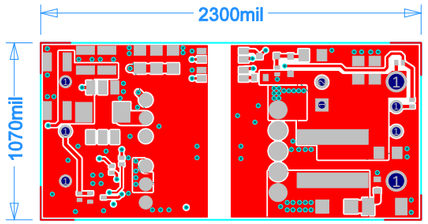
FABRICATION CHART

FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT	
			EXTERNAL	INTERNAL
☐ 0.031	■ LAYER 1	■ LAYER 1	☐ 1 OZ.	☐ 1 OZ.
■ 0.062	■ LAYER 4	■ LAYER 4	■ 2 OZ.	■ 2 OZ.
☐ 0.093	☐ NONE	☐ NONE	☐ OTHER ____	☐ OTHER ____
☐ 0.125				

DESIGN	TRACE/GAP SPACING	LAYER COUNT	
☐ SMD	■ 0.010/0.010	☐ SINGLE SIDED	☐ 2 LAYER
☐ THRU-HOLE	☐ 0.008/0.007	■ 4 LAYER	☐ 6 LAYER
■ MIX	☐ 0.006/0.006	☐ 8 LAYER	☐ 10 LAYER
		☐ OTHER ____	

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.
2. BASE LAMINATE: PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 OR EQUIVALENT, W/Tg =140 Deg C OR HIGHER. MINIMUM COMPOSITION TEMP (Td) OF 320 Deg c.
   GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 4 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3. SOLDERMASK: SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINAL ASSEMBLY AS A RESULT.
4. TOLERANCES: UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE +/- .005 INCHES, HOLE DIAMETERS SHALL BE +/- .003 INCHES.
5. PLATING: HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
6. FINISH: PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0003" to .0005" THICK ALL EXPOSED AREAS
   AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
7. LEGEND: IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
8. MARKINGS: BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
9. WORKMANSHIP: BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
10. DOCUMENTATION: PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
11. DRILL SIZES: HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
12. PANEL BORDER: ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
13. PROCESS CHANGES: NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.



TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
		Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP7451	Rev. A	L1												FB
Date: {Start Date}	Filename: PMP7451.PCB	Engineer: B.KING	PCB Dsgnr: R.SMITH	Modified Date: {Modification Date}								Software PADs		

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